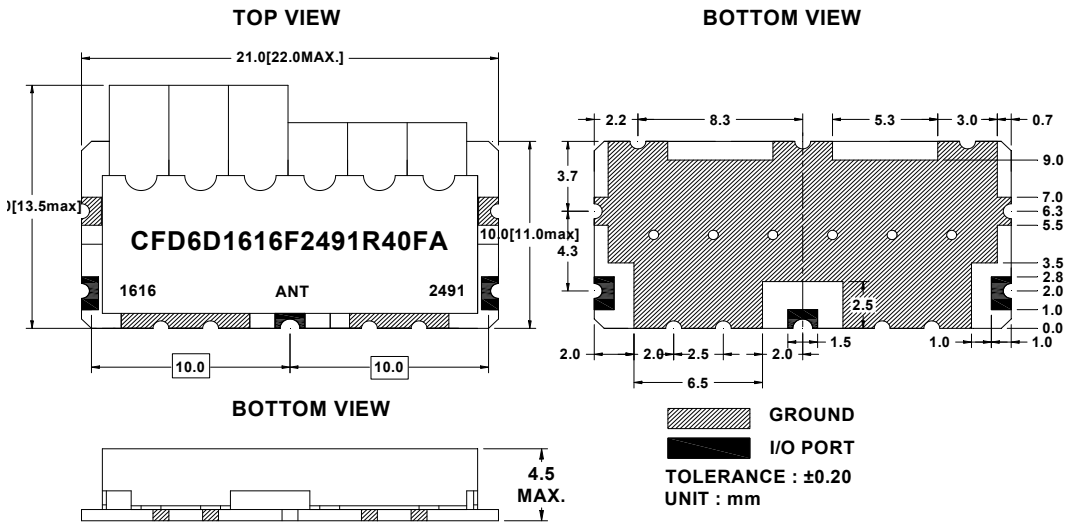
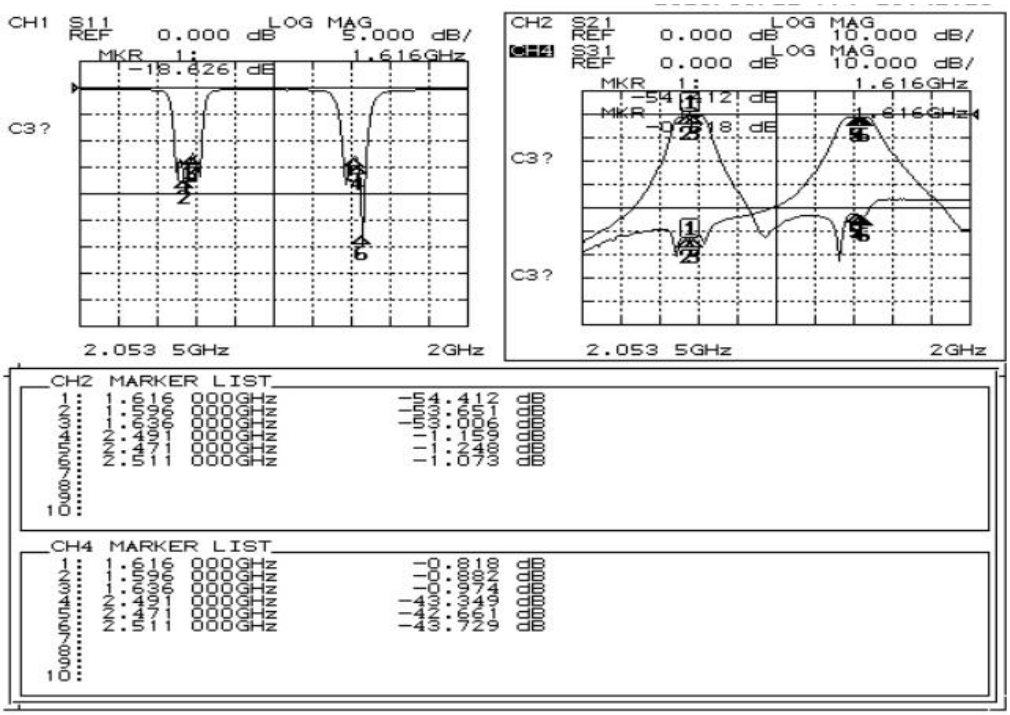
Electrical Specification

ITEMS	ANT >> Low	ANT >> High	UNIT
Center Frequency [fo]	1616.0	2491.0	MHz
Bandwidth [BW]	fo ±20.0 [1596.0~1636.0]	fo ±20.0 [2471.0~2511.0]	MHz
Insertion Loss in BW	2.5	2.5	dB max
Ripple in BW	1.0	1.0	dB max
Return Loss in BW			dB min
Attenuation ☐ Absolute Value ☑ Relative Value	35 dBc min. @ [2471~2511]	55 dBc min. @[1596~1636]	MHz
	dBc min. @ [~]	dBc min. @ [~]	MHz
	dBc min. @ [~]	dBc min. @ [~]	MHz
	dBc min. @ [~]	dBc min. @ [~]	MHz
Group Delay Variation			ns max
Input Power	3.0		W max.
In/Out Impedance	50 Ω		
Operation Temperature Range	-40℃ to +85℃		

Mechanical Specification

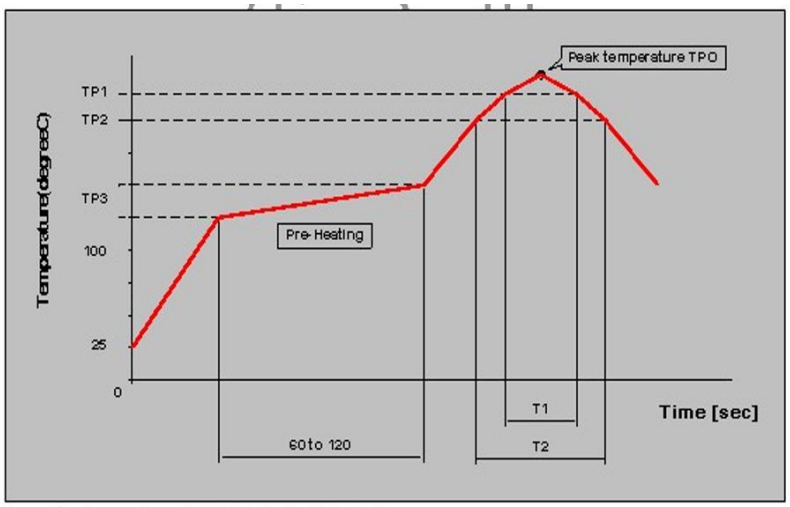


Plot Data



Recommanded PC Board Pattern

Soldering Condition



Measuring point of temperature : IN-OUT Terminals of The Device

Reflow Soldering : Both Convection and Infrared Rays, Hot Air and Hot Plate

Reflow standard condition	TPO (℃)	TP1 (℃)	T1 (s)	TP2 (℃)	T2 (s)	TP3 (℃)
Sn-3Ag-0.5 solder	245+/-5	220	30 to 60	___	___	150 to 180
Test condition of reflow heat resistance	260+5/-0	240	20	220	70	150 to 180